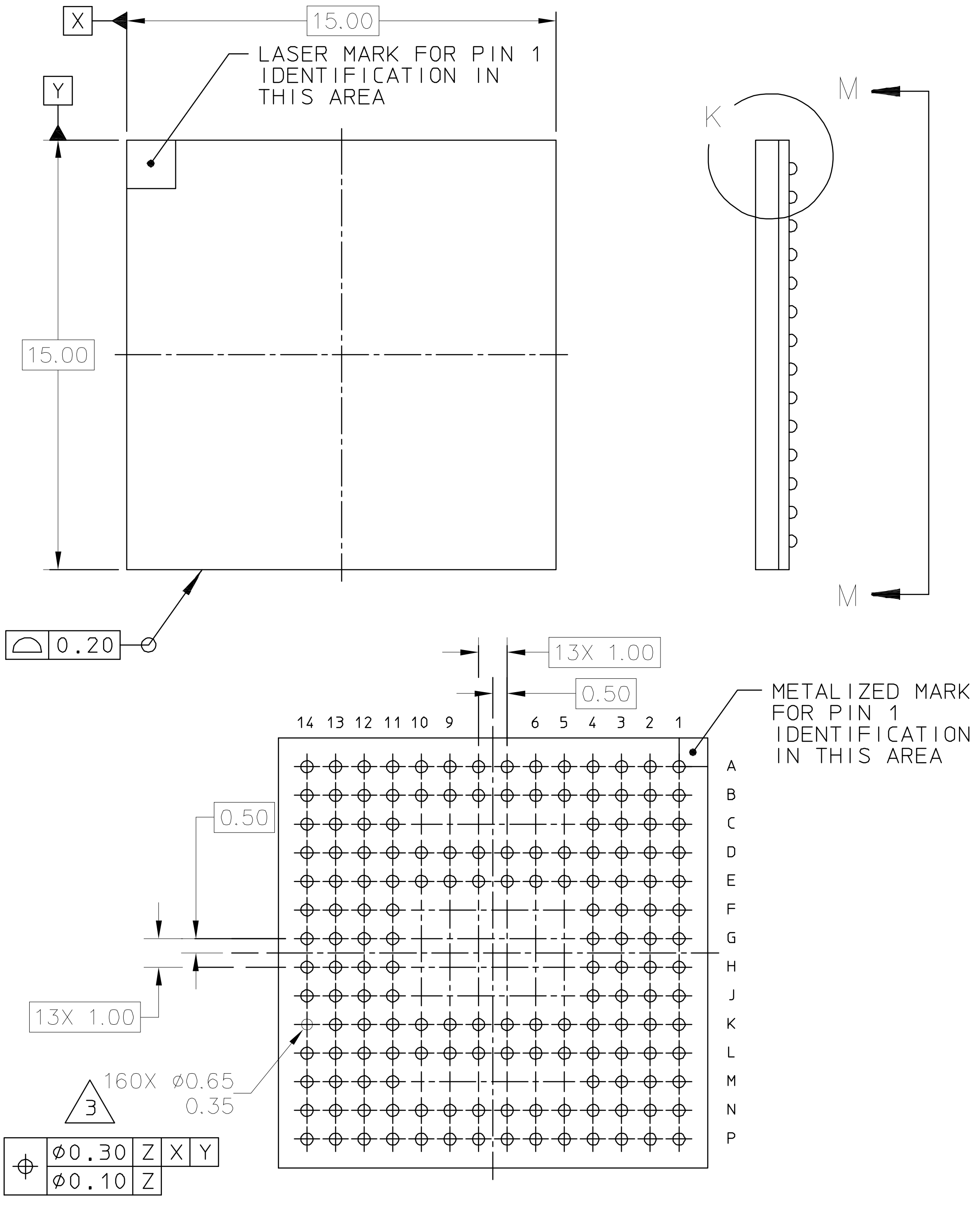

VIEW M—M

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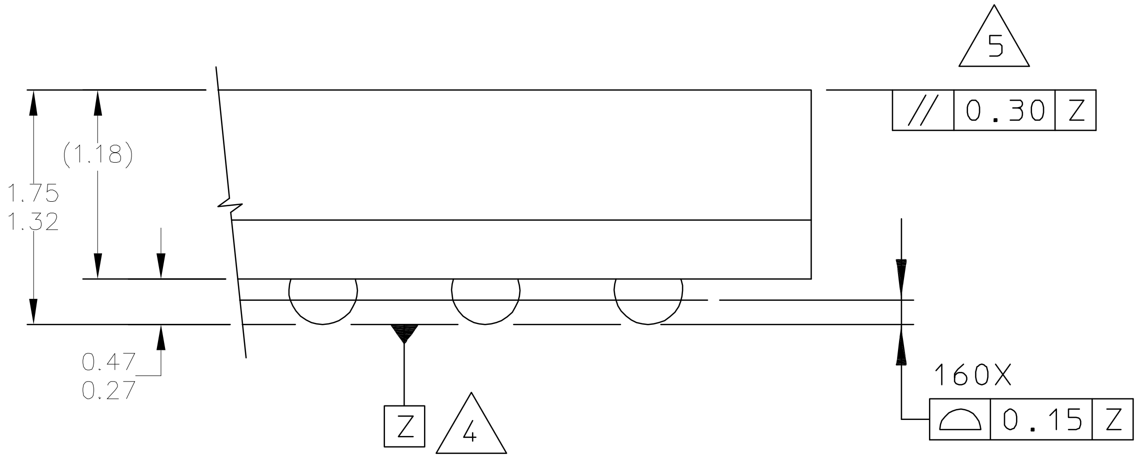
TITLE: 160 I/O STD MAP BGA, 15 X 15 PACKAGE	DOCUMENT NO: 98ARH98140A REV: B
	STANDARD: NON-JEDEC
	SOT1543-1 11 MAR 2016



DETAIL K

ROTATED 90° CLOCKWISE

	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 160 I/O STD MAP BGA, 15 X 15 PACKAGE	DOCUMENT NO: 98ARH98140A	REV: B
	STANDARD: NON-JEDEC	
	SOT1543-1	11 MAR 2016

NOTES

1. DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

△3 DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE Z.

△4 DATUM Z (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

△5 PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:
160 I/O STD MAP BGA,
15 X 15 PACKAGE

DOCUMENT NO: 98ARH98140A REV: B

STANDARD: NON-JEDEC

SOT1543-1 11 MAR 2016